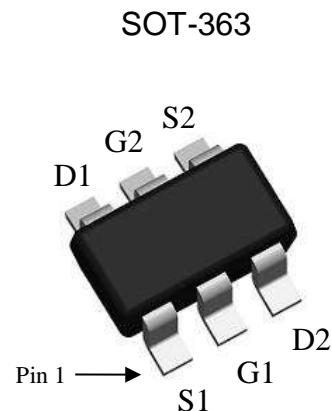


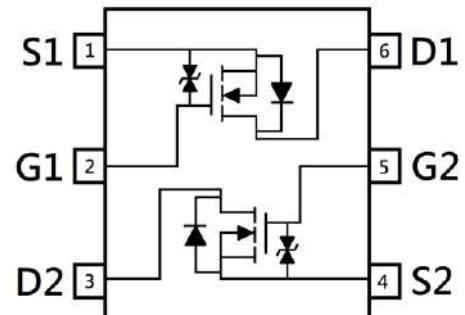
## Dual N-Channel Enhancement Mode MOSFET

### Features:

- ESD protected gate, typical 3kV (HBM)
- High speed switching
- Easily designed drive circuits
- Low-voltage drive
- Easy to use in parallel
- RoHS compliant package



$BV_{DSS}$	20V
$I_D @ V_{GS}=4.5V, T_A=25^\circ C$	0.63A
$R_{DS(ON)} \text{ typ.} @ V_{GS}=4.5V, I_D=0.2A$	0.32Ω
$R_{DS(ON)} \text{ typ.} @ V_{GS}=2.5V, I_D=0.2A$	0.4Ω
$R_{DS(ON)} \text{ typ.} @ V_{GS}=1.8V, I_D=0.2A$	0.8Ω



G : Gate S : Source D : Drain

### Ordering Information

Device	Package	Shipping
KWDK9	SOT-363 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel



### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ )

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	
Continuous Drain Current @ $V_{GS}=4.5\text{V}$ , $T_A=25^\circ\text{C}$	$I_D$	0.63	A
Continuous Drain Current @ $V_{GS}=4.5\text{V}$ , $T_A=70^\circ\text{C}$		0.50	
Pulsed Drain Current	$I_{DM}$	2.5	
Continuous Body Diode Forward Current @ $T_A=25^\circ\text{C}$	$I_S$	0.2	
ESD susceptibility	$V_{ESD}$	3000	V
Total Power Dissipation @ $T_A=25^\circ\text{C}$	$P_D$	0.3	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55~+150	°C

### Thermal Data

Parameter	Symbol	Steady State	Unit
Thermal Resistance, Junction-to-ambient	$R_{\theta JA}$	417	°C/W

Note:

\*a. Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}=150^\circ\text{C}$ . Ratings are based on low frequency and low duty cycles to keep initial  $T_J=25^\circ\text{C}$ .

\*b. Human body model,  $1.5\text{k}\Omega$  in series with  $100\text{pF}$ .

### Electrical Characteristics ( $T_A=25^\circ\text{C}$ , unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
<b>Static</b>					
BV <sub>DSS</sub>	20	-	-	V	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA
V <sub>GS(th)</sub>	0.3	-	1.2		V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA
G <sub>FS</sub>	-	1	-	S	V <sub>DS</sub> =5V, I <sub>D</sub> =0.2A
I <sub>GSS</sub>	-	-	±10		V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V
I <sub>DSS</sub>	-	-	1	μA	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V
R <sub>DSON</sub>	-	0.32	0.45		V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.2A
	-	0.4	0.6		V <sub>GS</sub> =2.5V, I <sub>D</sub> =0.2A
	-	0.8	1.2		V <sub>GS</sub> =1.8V, I <sub>D</sub> =0.2A
<b>Dynamic</b>					
C <sub>iss</sub>	-	32	-	pF	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f=1MHz
C <sub>oss</sub>	-	19	-		
C <sub>rss</sub>	-	17	-		
Q <sub>g</sub> *1, 2	-	0.8	-	nC	V <sub>DS</sub> =10V, I <sub>D</sub> =0.2A, V <sub>GS</sub> =4.5V
Q <sub>gs</sub> *1, 2	-	0.2	-		
Q <sub>gd</sub> *1, 2	-	0.15	-		
t <sub>d(ON)</sub> *1, 2	-	4.8	-	ns	V <sub>DS</sub> =10V, I <sub>D</sub> =0.2A, V <sub>GS</sub> =4.5V, R <sub>GS</sub> =10Ω
t <sub>r</sub> *1, 2	-	16	-		
t <sub>d(OFF)</sub> *1, 2	-	20	-		
t <sub>f</sub> *1, 2	-	15.6	-		
<b>Source-Drain Diode</b>					
V <sub>SD</sub> *1	-	0.8	1.2	V	I <sub>S</sub> =0.2A, V <sub>GS</sub> =0V
trr	-	7	-	ns	I <sub>F</sub> =0.2A, dI <sub>F</sub> /dt=100A/μs
Qrr	-	1	-		

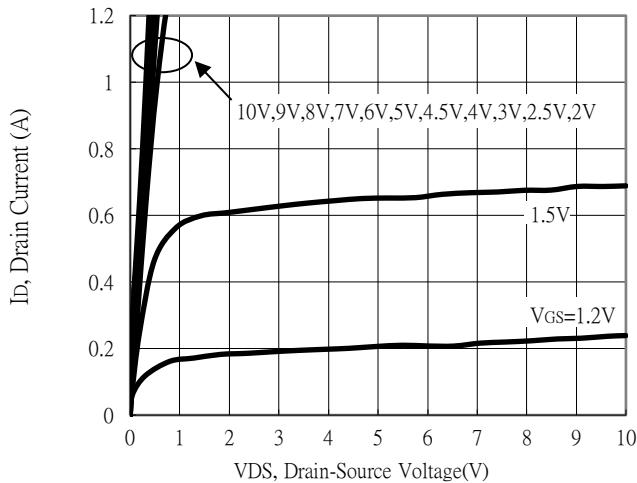
Note:

\*1. Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$

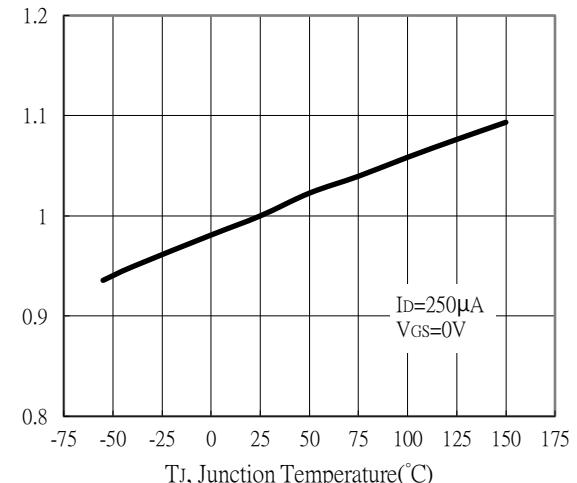
\*2. Independent of operating temperature

## Typical Characteristics

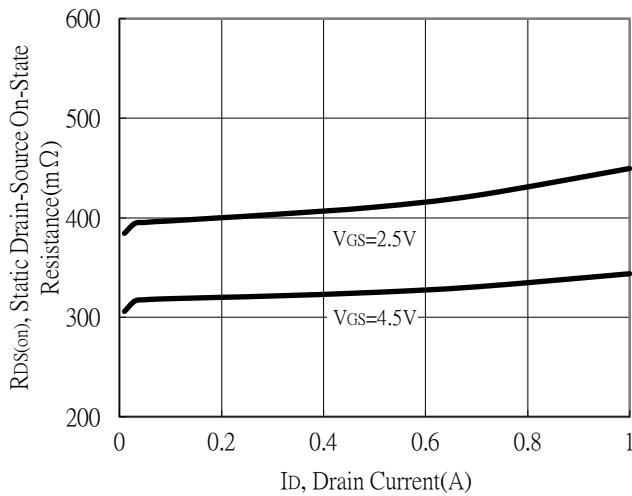
Typical Output Characteristics



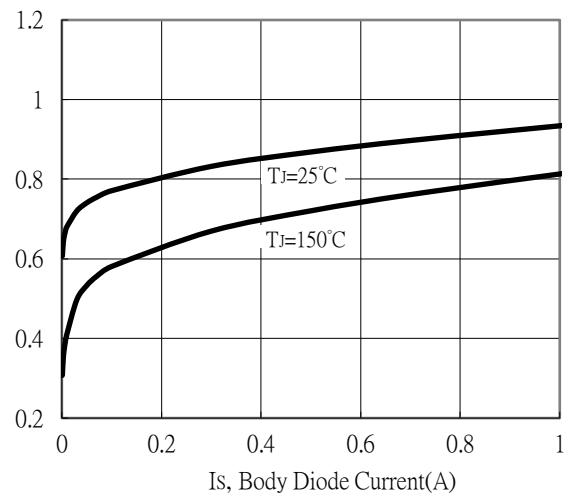
Breakdown Voltage vs Junction Temperature



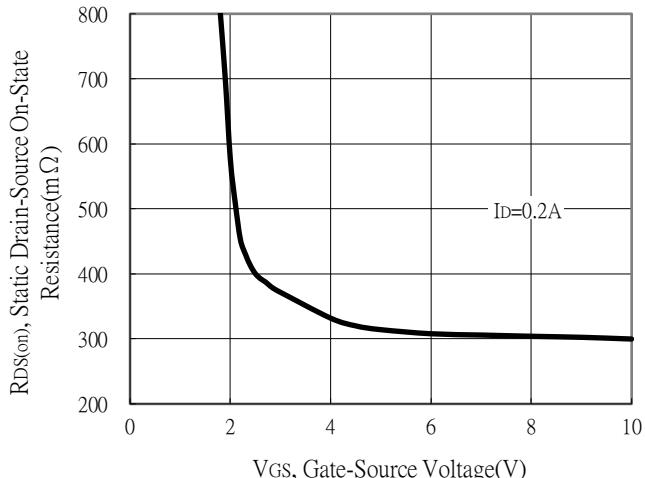
Static Drain-Source On-State resistance vs Drain Current



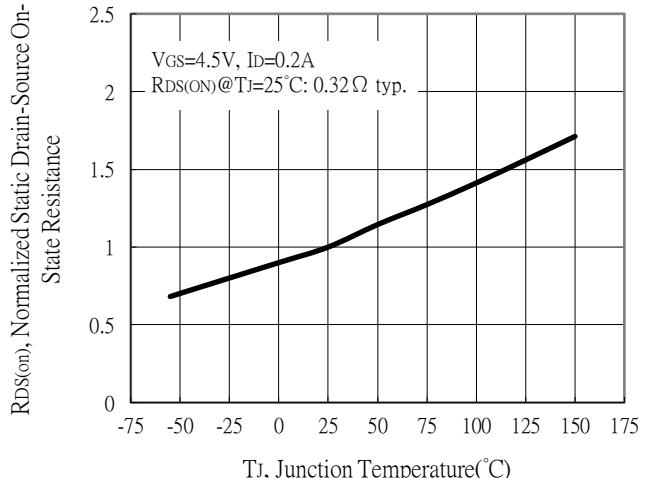
Body Diode Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

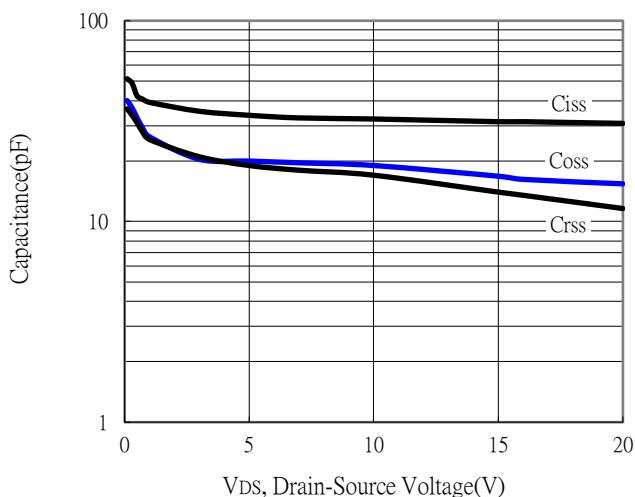


Drain-Source On-State Resistance vs Junction Temperature

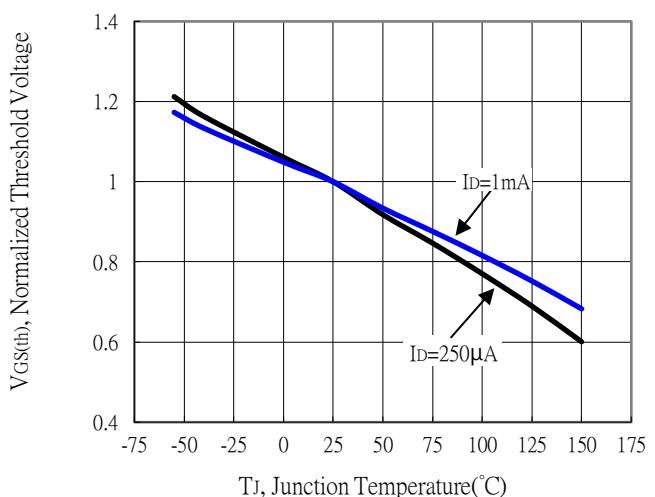


## Typical Characteristics (Cont.)

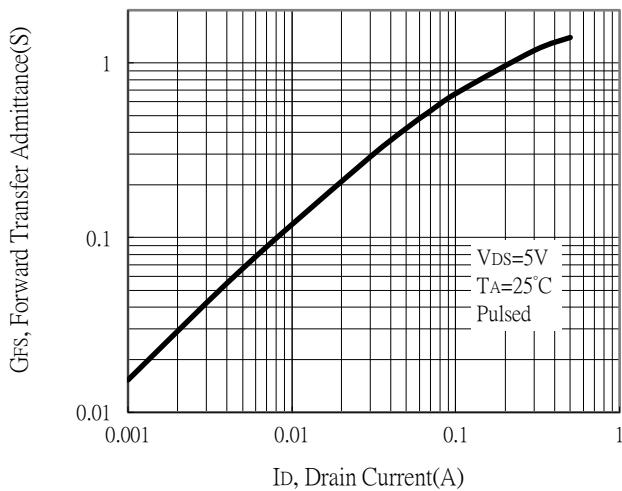
Capacitance vs Drain-to-Source Voltage



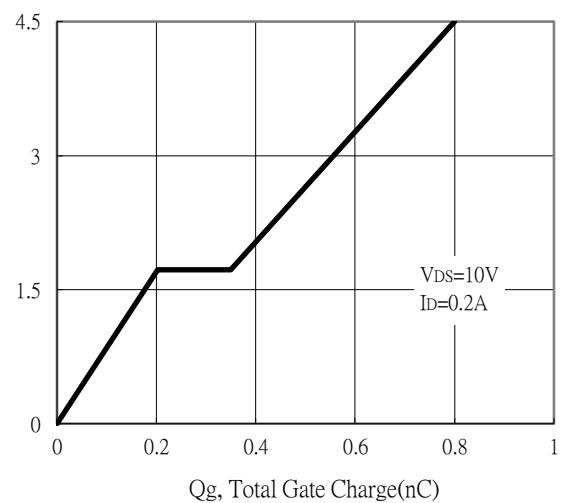
Threshold Voltage vs Junction Temperature



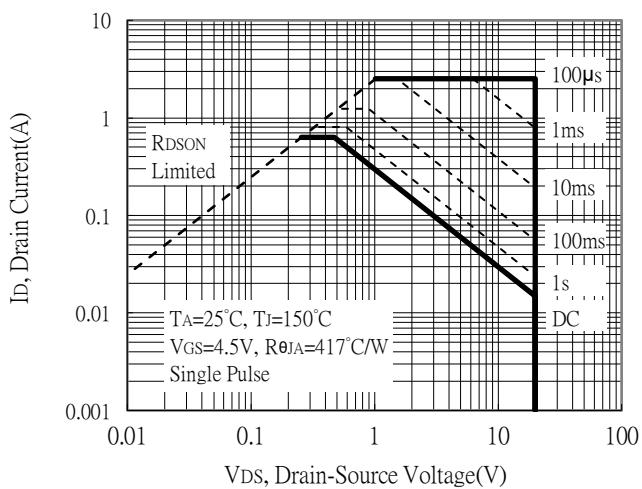
Forward Transfer Admittance vs Drain Current



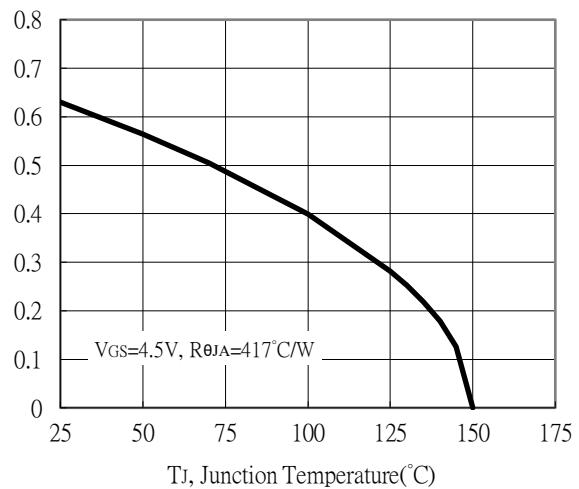
Gate Charge Characteristics



Maximum Safe Operating Area

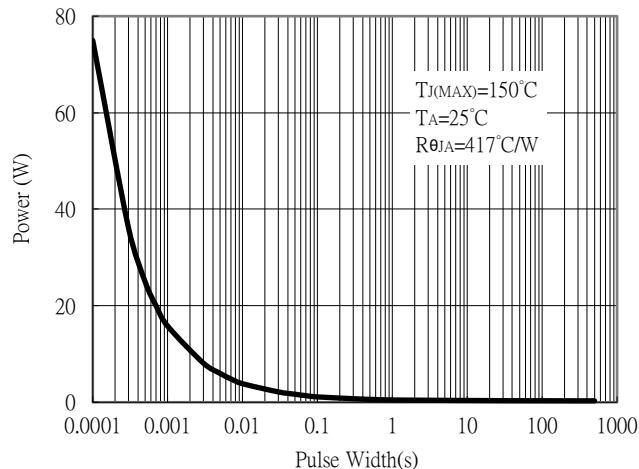


Maximum Drain Current vs Junction Temperature

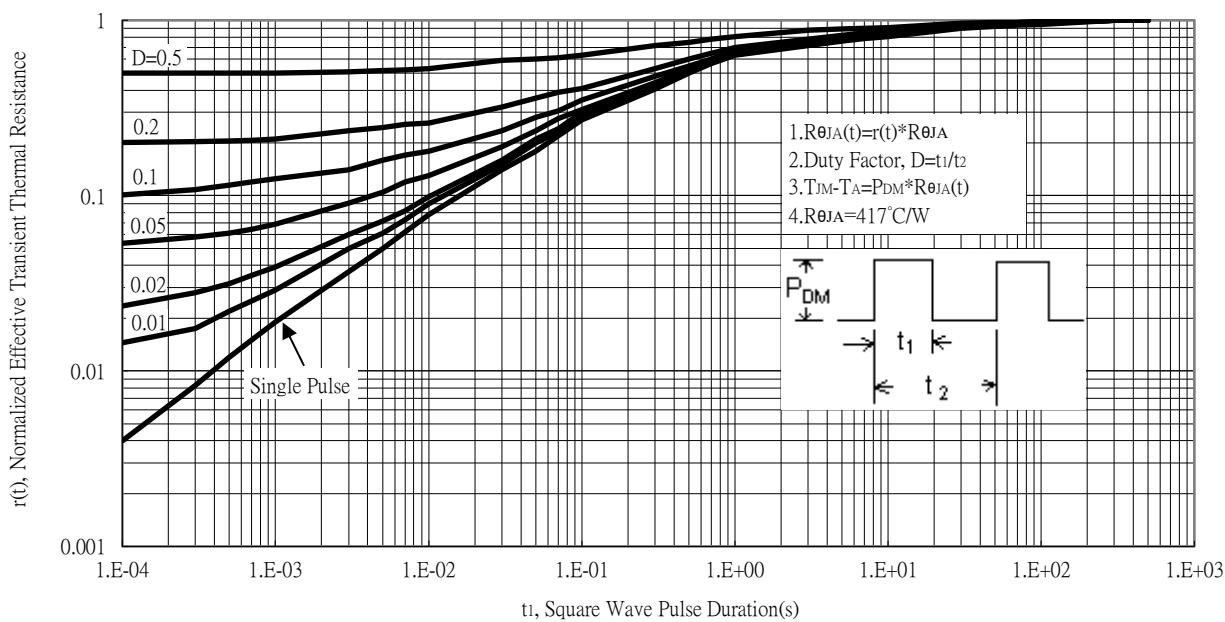


## Typical Characteristics (Cont.)

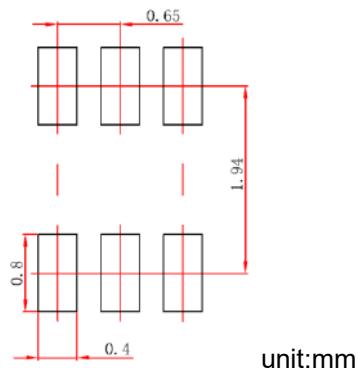
Single Pulse Power Rating, Junction to Ambient



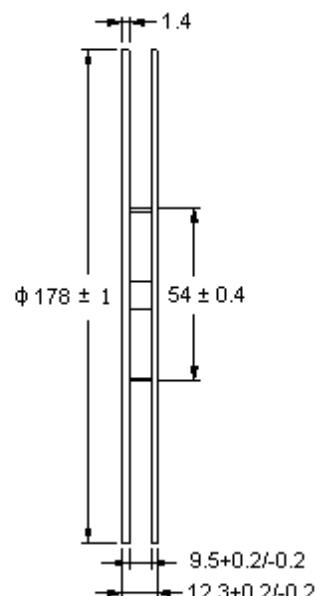
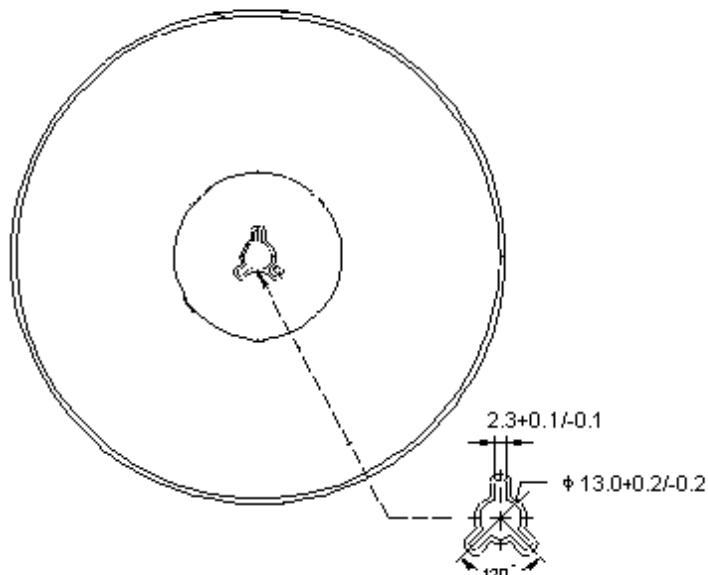
Transient Thermal Response Curves



## Recommended Soldering Footprint

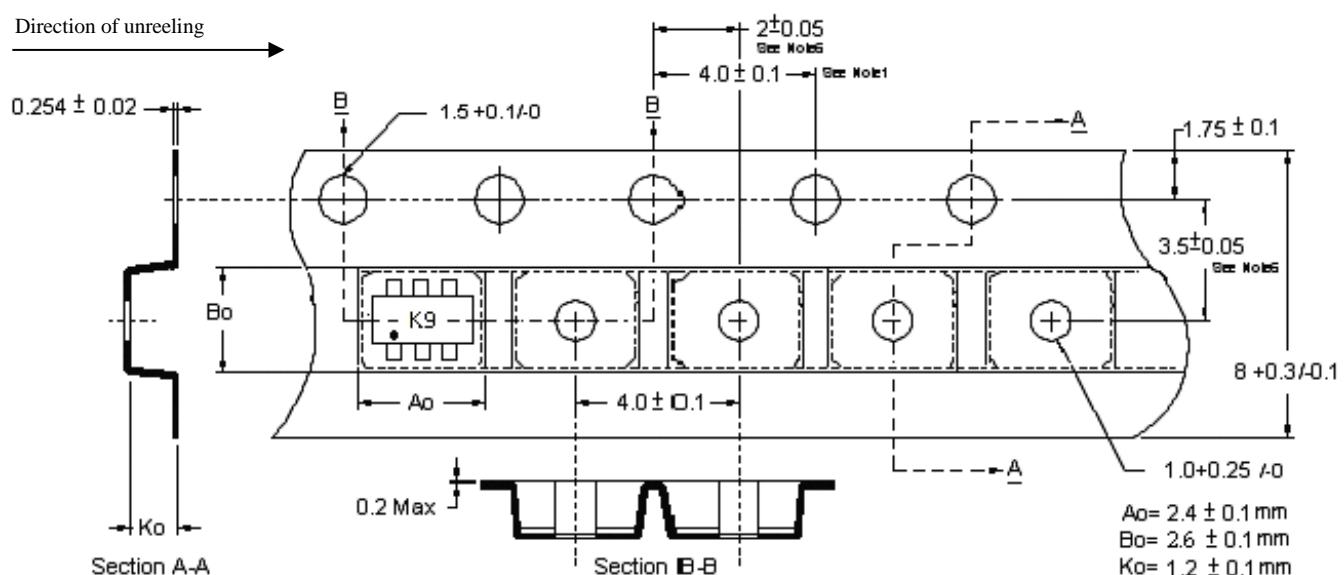


## Reel Dimension



Unit: millimeter

## Carrier Tape Dimension

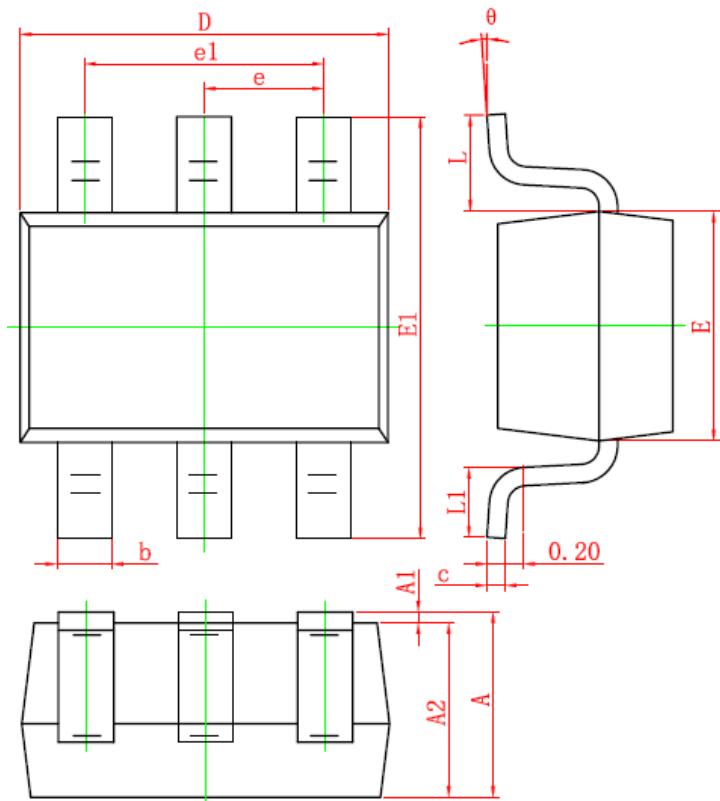


### Notes:

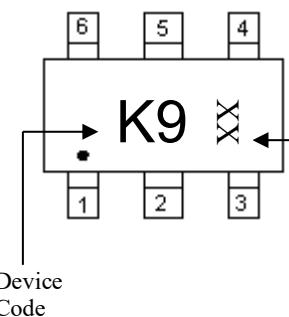
1. 10 sprocket hole pitch cumulative tolerance  $\pm 0.2$ .
2. Camber not to exceed 1mm in 100mm.
3. Material: Conductive Black Polystyrene.
4.  $A_0$  &  $B_0$  measured on a plane 0.3mm above the bottom of the pocket.
5.  $K_0$  measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Unit : millimeter

## SOT-363 Dimension



### Marking:



6-Lead SOT-363 Plastic  
Surface Mounted Package

### Style:

- Pin 1. Source1 (S1)
- Pin 2. Gate1 (G1)
- Pin 3. Drain2 (D2)
- Pin 4. Source2 (S2)
- Pin 5. Gate2 (G2)
- Pin 6. Drain1 (D1)

Date Code:  
 Year + Month  
 Year : 9→2019,  
 0→2020,..., etc  
 Month : 1→Jan  
 2→Feb, ..., 9→  
 Sep, A→Oct, B  
 →Nov, C→Dec

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043	E1	2.150	2.450	0.085	0.096
A1	0.000	0.100	0.000	0.004	e	0.650	TYP	0.026	TYP
A2	0.900	1.000	0.035	0.039	e1	1.200	1.400	0.047	0.055
b	0.150	0.350	0.006	0.014	L	0.525	REF	0.021	REF
c	0.080	0.150	0.003	0.006	L1	0.260	0.460	0.010	0.018
D	2.000	2.200	0.079	0.087	θ	0°	8°	0°	8°
E	1.150	1.350	0.045	0.053					